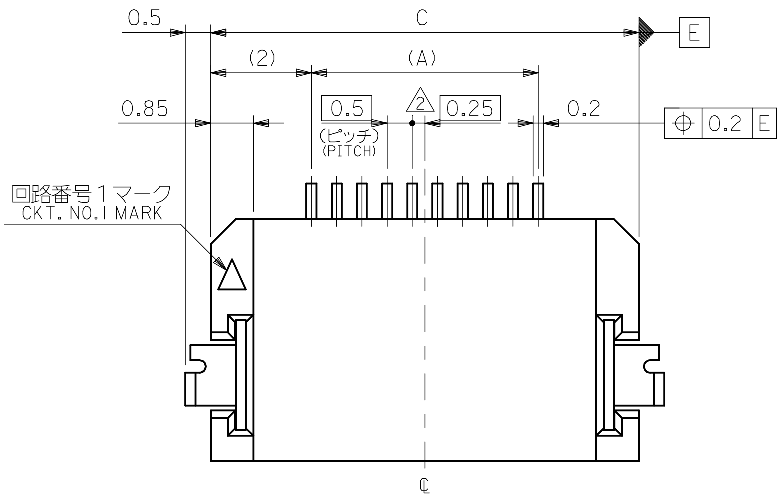
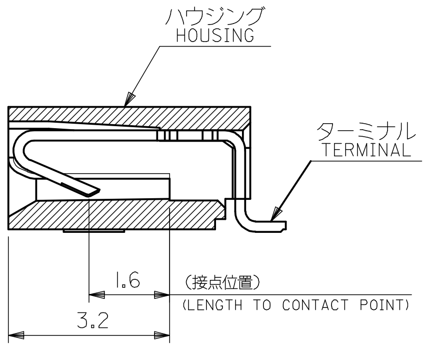




SECT. X-X

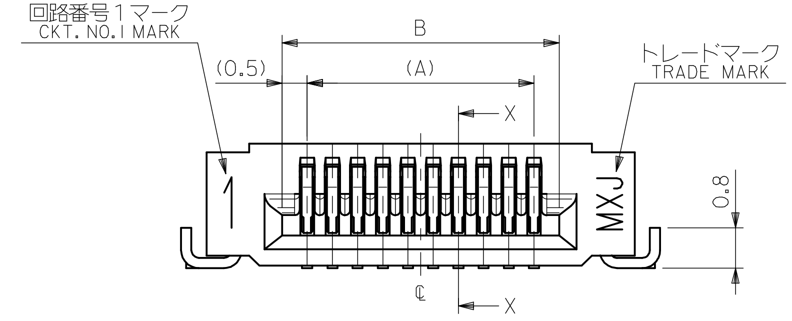
注記 NOTES

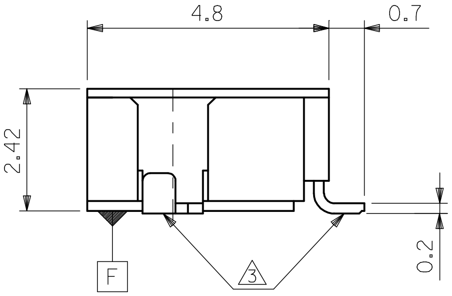
1. 材質 MATERIAL
   ハウジング： PPHS, UL94V-0
   HOUSING : PPHS, UL94V-0
   ターミナル：リン青銅（t＝0. 2）、ニッケル下地　錫ビスマスメッキ
   TERMINAL : PHOS-BRO.(t=0.2), TIN-BISMUSTH OVER NICKEL PLATING
   金具：リン青銅（t＝0. 2）、ニッケル下地　錫メッキ
   FITTING NAIL : PHOS-BRO.(t=0.2), TIN OVER NICKEL PLATING

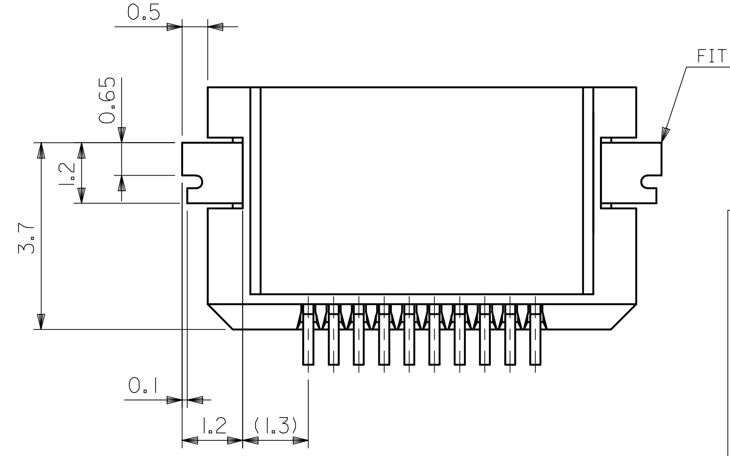
2. 偶数極に適用。
   APPLY FOR EVEN CIRCUIT.

3. ソルダーテール半田付け面及び金具半田付け面のズレ量は、
   基準面 F に対し、上方向 0.1 MAX.
   下方向 0.15MAX. とする。
   MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS
   FROM F : UPPER DIRECTION 0.1 MAX.
   : LOWER DIRECTION 0.15MAX.

4. 本製品は 52975−＊＊40 の鉛フリー品である。
   THIS PRODUCT IS LEAD FREE OF 52975-**40







C	B	A	EMBOSSED TAPE ORDER No. オーダー番号	MATERIAL NO.	極数 NO. OF CKT.
16.5	13.5	12.5	52975-2683	52975-2649	26
15.5	12.5	11.5	-2483	-2449	24
14.0	11.0	10.0	-2183	-2149	21
13.0	10.0	9.0	-1983	-1949	19
12.5	9.5	8.5	-1883	-1849	18
12.0	9.0	8.0	-1783	-1749	17
11.5	8.5	7.5	-1683	-1649	16
11.0	8.0	7.0	-1583	-1549	15
10.0	7.0	6.0	-1383	-1349	13
9.5	6.5	5.5	-1283	-1249	12
9.0	6.0	5.0	-1183	-1149	11
8.5	5.5	4.5	-1083	-1049	10
8.0	5.0	4.0	-0983	-0949	9
7.5	4.5	3.5	-0883	-0849	8
7.0	4.0	3.0	-0783	-0749	7
6.5	3.5	2.5	52975-0683	52975-0649	6

52975-**49	MODEL NO.

REVISED
EC NO: J2009-2004 2009/02/27
DRWN:MTAKASAKI 2009/02/27
CH'KD:MHAYASHI 2009/02/27
APPR:NUKITA
DESCRIPTION
C
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

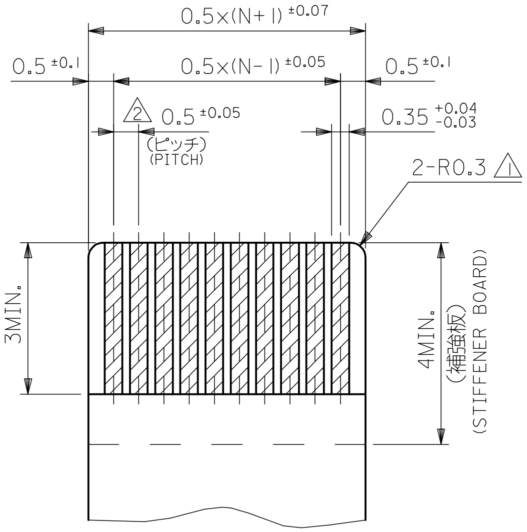
DRAWN BY	H.SHIMABUKUR	DATE 2004/02/09
CHECKED BY	K.TOJO	DATE 2004/02/09
APPROVED BY	M.SASAO	DATE 2004/02/09

TITLE
0.5 FFC/FPC CONN.NON-ZIF
HSG ASSY(UPR CONT)
-LEAD FREE-

molex MOLEX INCORPORATED

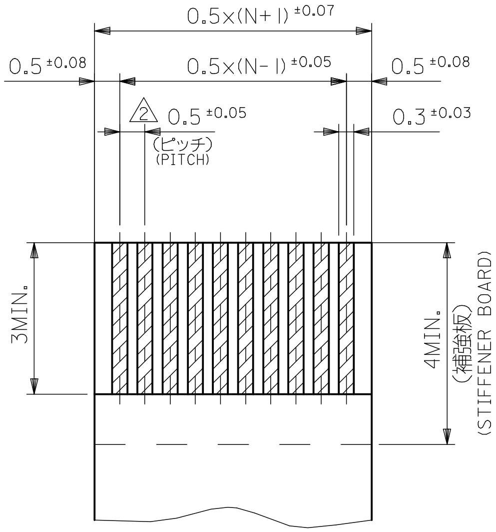
MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-52975-014
SHEET NO.: 1 OF 2
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



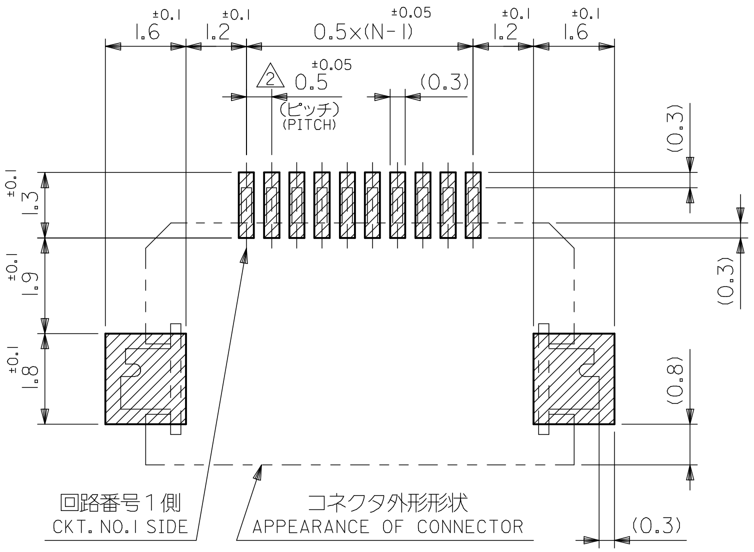
適合ＦＰＣ推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION

(仕上がり厚さ：0.3±0.03)
(THICKNESS : 0.3±0.03)



適合ＦＦＣ推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION

(仕上がり厚さ：0.3±0.03)
(THICKNESS : 0.3±0.03)



参考基板レイアウト
REFERENCE P.C.BOARD
PATTERN DIMENSION

(マウント面)
(MOUNTING SIDE)

注記 NOTES

1 R0.3 は、ＦＰＣの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

2 公差非累積のこと。
NON-ACCUMULATIVE.

3 ＦＰＣについて：
打抜き方向は導体側から補強板を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED
EC NO: J2009-2004
DRWN:MTAKASAKI 2009/02/27
CH'KD:MHAYASHI 2009/02/27
APPR:NUKITA 2009/02/27
DESCRIPTION
REV C

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±3 °	

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

52975-**49 MODEL NO.

DIMENSION STYLE	MM ONLY
SCALE	---
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	H.SHIMABUKUR
DATE	2004/02/09
CHECKED BY	K.TOJO
DATE	2004/02/09
APPROVED BY	M.SASAO
DATE	2004/02/09
TITLE	0.5 FFC/FPC CONN.NON-ZIF HSG ASSY(UPR CONT) -LEAD FREE-
MATERIAL NO.	SEE SHEET 1
DOCUMENT NO.	SD-52975-014
SHEET NO.	2 OF 2
SIZE	A3

molex MOLEX INCORPORATED